

L Number	Hits	Search Text	DB	Time stamp
45	4379783	hole recess trench gap cavity opening	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:39
46	1803241	substrate wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:39
47	1146415	electrode bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:39
48	18550	interconnect\$3 adj2 (pattern film layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:40
49	4664	(hole recess trench gap cavity opening) and (substrate wafer) and (electrode bump) and (interconnect\$3 adj2 (pattern film layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:44
50	2174	257/668	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:42
51	2981	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:42
52	748	257/688	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:42
53	340	257/694	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:42
54	2165	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:42
55	2938	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
56	2443	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
57	276	257/739	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43

58	3056	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
59	3556	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
60	957	257/782	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
61	1482	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
62	2329	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
63	2372	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
64	16528	257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/782 257/783 257/784 257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:43
65	488	((hole recess trench gap cavity opening) and (substrate wafer) and (electrode bump) and (interconnect\$3 adj2 (pattern film layer))) and (257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/782 257/783 257/784 257/786)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 15:44